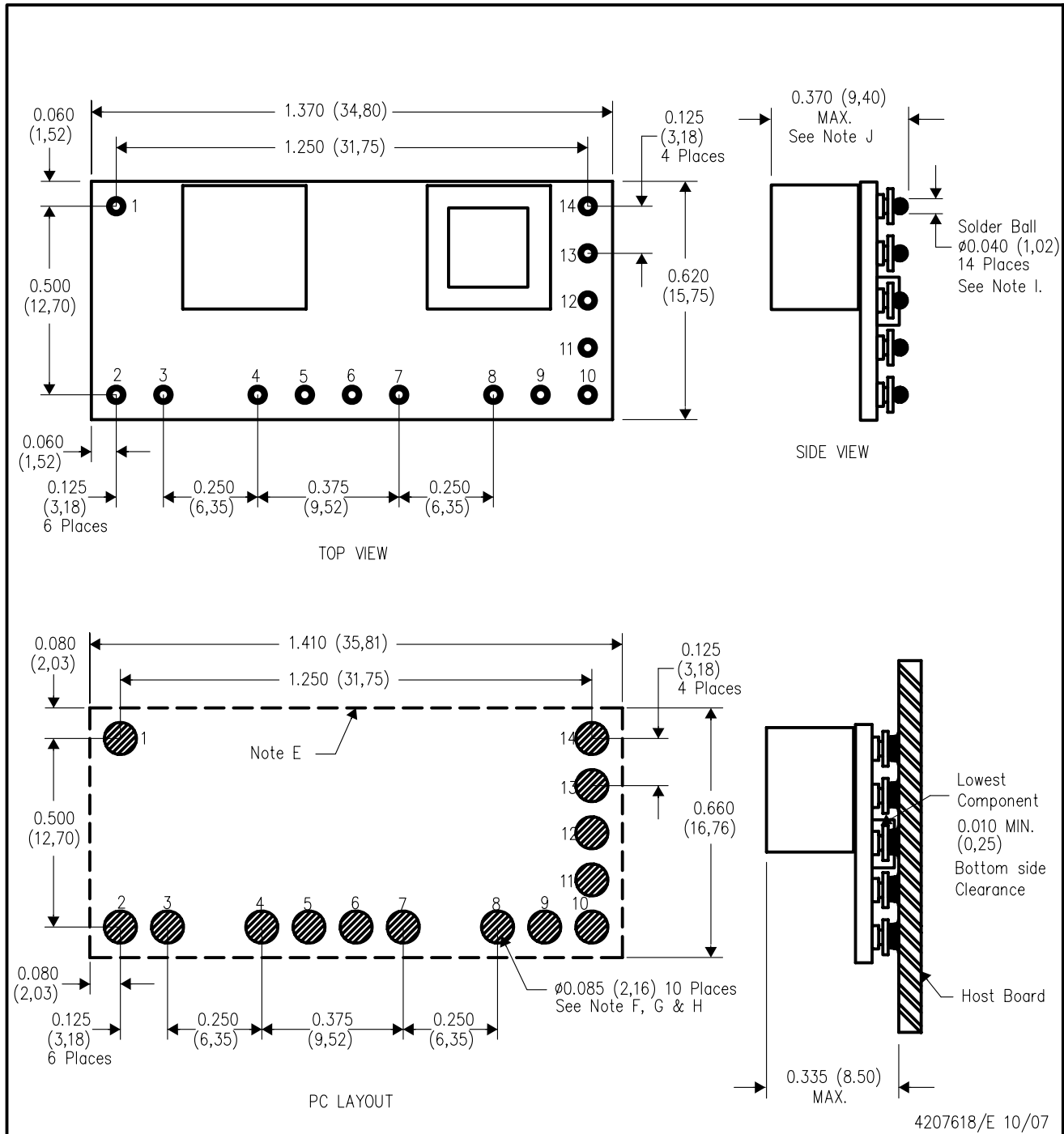


ECQ (R-PDSS-B14)

DOUBLE SIDED MODULE



- NOTES:
- A. All linear dimensions are in inches (mm).
 - B. This drawing is subject to change without notice.
 - C. 2 place decimals are ± 0.030 ($\pm 0,76$ mm).
 - D. 3 place decimals are ± 0.010 ($\pm 0,25$ mm).
 - E. Recommended keep out area for user components.
 - F. Power pin connection should utilize two or more vias to the interior power plane of 0.025 (0,63) I.D. per input, ground and output pin (or the electrical equivalent).
 - G. Paste screen opening: 0.080 (2,03) to 0.085 (2,16). Paste screen thickness: 0.006 (0,15).
 - H. Pad type: Solder mask defined.
 - I. All pins: Material – Copper Alloy
Finish – Tin (100%) over Nickel plate
Solder Ball – See product data sheet.
 - J. Dimension prior to reflow solder.

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